	-	6	(700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls. and ((detect\$3 or	USPAT;	2004/07/09 22:09
			sens\$3) with (die or die-to-die or area) with (semiconductor or wafer or	US-PGPUB;	
			semi-conductor))) and network.clm.	ЕРО; ЈРО;	
				DERWENT;	
				IBM_TDB	
	-	6903	((detect\$3 or sens\$3) with (die or die-to-die or area) with	USPAT;	2004/07/09 22:09
			(semiconductor or wafer or semi-conductor)) and ("detectors" or	US-PGPUB;	
			"sensors" or ((sens\$3 or detect\$4) near4 (plural\$4 or several or many)))	ЕРО; ЛРО;	
				DERWENT;	
		_	///	IBM_TDB	
	-	6	((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.)	USPAT;	2004/07/09 22:10
			and (((detect\$3 or sens\$3) with (die or die-to-die or area) with	US-PGPUB;	
			(semiconductor or wafer or semi-conductor)) and ("detectors" or	ЕРО; ЈРО;	
			"sensors" or ((sens\$3 or detect\$4) near4 (plural\$4 or several or	DERWENT;	
		48	many))))) and network.clm.	IBM_TDB	2004/07/00 22:10
	-	40	((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.) and (((detect\$3 or sens\$3) with (die or die-to-die or area) with	USPAT; US-PGPUB;	2004/07/09 22:10
			((detects) of sensys) with (die of die-to-die of area) with (semiconductor or wafer or semi-conductor)) and ("detectors" or	EPO; JPO;	
			"sensors" or ((sens\$3 or detect\$4) near4 (plural\$4 or several or	DERWENT;	
			many))))) and (network\$3 or server or LAN or WAN or SAN or ethernet	IBM_TDB	
			or intranet or internet)	IDM_IDD	
	_	4	((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.)	USPAT;	2004/07/09 22:12
	_		and (((detect\$3 or sens\$3) with (die or die-to-die or area) with	US-PGPUB;	2004/01/07 22.12
			(semiconductor or wafer or semi-conductor)) and ("detectors" or	ЕРО; ЛРО;	
			"sensors" or ((sens\$3 or detect\$4) near4 (plural\$4 or several or	DERWENT;	
i			many))))) and (international adj2 business).as.	IBM_TDB	
	_	3384	("detectors" or "sensors") and ((detect\$3 or sens\$3) with (die or	USPAT;	2004/07/09 22:14
			die-to-die or area) with (semiconductor or wafer or semi-conductor))	US-PGPUB;	
				ЕРО; ЛРО;	
				DERWENT;	
				IBM_TDB	
	-	1	((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.)	USPAT;	2004/07/09 22:14
			and (("detectors" or "sensors") and ((detect\$3 or sens\$3) with (die or	US-PGPUB;	
			die-to-die or area) with (semiconductor or wafer or semi-conductor))))	ЕРО; ЛРО;	
			and (international adj2 business).as.	DERWENT;	
				IBM_TDB	
	-	79	(438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.)	USPAT;	2004/07/09 22:15
			and (("detectors" or "sensors") and ((detect\$3 or sens\$3) with (die or	US-PGPUB;	
			die-to-die or area) with (semiconductor or wafer or semi-conductor)))	ЕРО; ЛРО;	
				DERWENT;	
			(420/5 10 1	IBM_TDB	2004107/10 07 07
	-	210	(438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.)	USPAT;	2004/07/10 02:07
			and (((detect\$3 or sens\$3) with (die or die-to-die or area) with	US-PGPUB;	
			(semiconductor or wafer or semi-conductor)) and ("detectors" or	EPO; JPO;	
			"sensors" or ((sens\$3 or detect\$4) near4 (plural\$4 or several or many))))	DERWENT;	
				IBM_TDB	

L Number	Hits	Search Text	DB	Time stamp
1	12691	438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.	USPAT;	2004/07/10 15:31
			US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
2	208	709/\$.ccls. and ((438/5-18.ccls. or	USPAT;	2004/07/10 16:45
		700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	220740	(1,4,402, 02) (41,41; 1; 4,1;	IBM_TDB	2004/07/10 15 21
3	238648	(detect\$3 or sens\$3) with (die or die-to-die or area)	USPAT;	2004/07/10 15:31
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
4	9115	(detect\$3 or sens\$3) with (die or die-to-die or area) with (semiconductor	USPAT;	2004/07/10 16:31
")113	or wafer or semi-conductor)	US-PGPUB;	2004/07/10 10.51
		water of senii-conductor)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	2149337	"detectors" or "sensors" or ((sens\$3 or detect\$4) near4 (plural\$4 or	USPAT;	2004/07/10 15:32
		several or many))	US-PGPUB;	
		***	ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
6	622719	"detectors" or "sensors"	USPAT;	2004/07/10 15:32
			US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
_	21.6720	((IBM_TDB	
7	216728	((sens\$3 or detect\$4) near4 (plural\$4 or several or many))	USPAT;	2004/07/10 15:32
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM_TDB	
8	2	20020103563.pn.	USPAT;	2004/07/10 15:32
	_	20020103303.pn.	US-PGPUB;	2004/07/10 15.52
l			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
14	17		USPAT	2004/07/10 15:47
		"5801965" "5862055" "5923430" "5949901" "5959459"		
		"5966459" "6016562" "6167448" "6246787" "6314379"		
		"6408219" "6438438").PN.		
17	61	5761064.URPN.	USPAT	2004/07/10 15:55
19	8	("6614520" "5737072" "6529621" "6587193").pn.	USPAT;	2004/07/10 16:37
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
20	24357	(detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or	IBM_TDB USPAT;	2004/07/10 16:43
20	24337	(electron near2 microscop\$2) or inspect\$4) with (die or die-to-die or	US-PGPUB;	200 4 /0//10 10.43
	,	area or shot or defect\$4) with (semiconductor or wafer or	ЕРО; ЛРО;	
		semi-conductor or pellicle)	DERWENT;	
			IBM TDB	
21	24382	(detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or	USPAT;	2004/07/10 18:13
		(electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4)	US-PGPUB;	
		with (die or die-to-die or area or shot or defect\$4) with (semiconductor	EPO; JPO;	
		or wafer or semi-conductor or pellicle)	DERWENT;	
			IBM_TDB	

			·	
22	372	((detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4)	USPAT; US-PGPUB;	2004/07/10 17:03
		with (die or die-to-die or area or shot or defect\$4) with (semiconductor	EPO; JPO;	
		or wafer or semi-conductor or pellicle)) and (distribut\$43 near2 (node or	DERWENT;	
		process\$3))	IBM TDB	
23	42247	709/\$.ccls. or ((438/5-18.ccls. or	USPAT;	2004/07/10 19:02
		700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.))	US-PGPUB,	
1	1		EPO; JPO;	
			DERWENT;	
0.4		(// 1	IBM_TDB	2004/07/10 16 50
24	65	(((detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or	USPAT; US-PGPUB;	2004/07/10 16:58
		(electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor	ЕРО; ЛРО;	
		or wafer or semi-conductor or pellicle)) and (distribut\$43 near2 (node or	DERWENT;	
		process\$3))) and (709/\$.ccls. or ((438/5-18.ccls. or	IBM_TDB	
		700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.)))		
25	2	6049895.URPN.	USPAT	2004/07/10 16:48
26	2	6629002.pn.	USPAT;	2004/07/10 16:59
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM_TDB	
27	2	6711731.pn.	USPAT;	2004/07/10 16:59
21		0711731.pm.	US-PGPUB;	2004/07/10 10:57
			ЕРО; ЛРО;	
			DERWENT,	
			IBM_TDB	
28	404	((detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or	USPAT;	2004/07/10 17:07
		(electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4)	US-PGPUB;	
		with (die or die-to-die or area or shot or defect\$4) with (semiconductor	ЕРО; ЛРО;	
		or wafer or semi-conductor or pellicle)) and ((distribut\$4 near2 (node)) or network\$3 or ethernet or internet or LAN or WAN or SAN or	DERWENT; IBM_TDB	
		area-network\$3 or areanetwork\$3 or computernetwork\$3 or ((transfer or	IDM_1DD	
		communicat\$4) near2 (path or link\$3))).clm.		
29	539	((detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or	USPAT;	2004/07/10 17:28
		(electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4)	US-PGPUB;	·
		with (die or die-to-die or area or shot or defect\$4) with (semiconductor	ЕРО; ЈРО;	
		or wafer or semi-conductor or pellicle)) and ((distribut\$4 near2 (node))	DERWENT;	
		or network\$3 or rout\$3 or ethernet or internet or LAN or WAN or SAN	IBM_TDB	
		or area-network\$3 or areanetwork\$3 or computernetwork\$3 or ((transfer or communicat\$4) near2 (path or link\$3))).clm.		
30	68	(709/\$.ccls. or ((438/5-18.ccls. or	USPAT;	2004/07/10 17:21
1	00	700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.))) and (((detect\$3	US-PGPUB;	200-007710 17.21
		or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or (electron	ЕРО; ЛРО;	
		near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4) with (die	DERWENT;	
		or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or	IBM_TDB	
		semi-conductor or pellicle)) and ((distribut\$4 near2 (node)) or		,
		network\$3 or rout\$3 or ethernet or internet or LAN or WAN or SAN or		
		area-network\$3 or areanetwork\$3 or computernetwork\$3 or ((transfer or communicat\$4) near2 (path or link\$3))).clm.)		
31	43	700/\$.ccls. and (((detect\$3 or sens\$3 or metrology or measur\$5 or	USPAT;	2004/07/10 17:31
31	43	scan\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3	US-PGPUB;	2007/07/10 17:31
		or rasterscan\$4) with (die or die-to-die or area or shot or defect\$4) with	ЕРО; ЈРО;	
		(semiconductor or wafer or semi-conductor or pellicle)) and	DERWENT;	
		((distribut\$4 near2 (node)) or network\$3 or rout\$3 or ethernet or	IBM_TDB	
		internet or LAN or WAN or SAN or area-network\$3 or areanetwork\$3		
		or computernetwork\$3 or ((transfer or communicat\$4) near2 (path or		
		link\$3))).clm.)		L

2004/07/10 17:22	20	_	(700/# 1 1///14 /#2 #2 4 1 #5	LICDATE	2004/07/10 17 22
a	32	5			2004/07/10 17:22
(semiconductor or wafer or semi-conductor or pellicle)) and ((shirth/l4 near2 (node)) or networks 37 or rout53 or rethermet or internet or LAN or WAN or SAN or accu-network33 or areanetwork33 or semsors 30 or computentework35 or (transfer or communicat54) near (path or intx53))) elm.) pont ((799/5 cels. or (438/5-18 cels.)) and (((detects3 or sems33 or metrology or measur55 or sears4 or SEM or (electron near2 microscop52) or inspect4 or raster53 or rastersean54) with (die or die-to-die or area or shot or defect54) with (semiconductor or wafer or semi-conductor or pellicle) and ((distribut54 near2 (node)) or communicat54) near2 (path or inix53)), jbm.)) 34					
((distribut34 near2 (node)) or network33 or rout35 or ethernet or internet or LAN or WAN or SAN or area-network35 or computernetwork35 or ((transfer or communicat34) near2 (path or inick39), (lem.)) not ((700% Sects. or (4385-18 cells. or 700/1-4,19.20)5,15.9.90.95,96,108-110,117,121 (cells.))) and ((detect33 or sent) or near2 microscop52) or inspect34 or raster33 or rasterscan434) with (die or diet-of-die or area or shot or defect34) with (senticonductor or wafer or senti-conductor or pellicle)) and ((distribut34 near2 (node)) or network35 or or computernetwork35 or ((transfer or communicat34)) near2 (path or link33)); bim.)) 433					
internet or I.AN or WAN or SAN or area-network\$3 or areanetwork\$3 or areanetwork\$3 or areanetwork\$3 or areanetwork\$3 or areanetwork\$3 or computemetwork\$3 or (fransfer or communicat\$4) near (path of 1970) not (709/8 cels. or (438/5-18 cels. or 709/1-4,19.20,51,59.90,95.56,108-110,117,121 cels.))) and ((detect\$3 or sens\$3 or metrology or measur\$5 or sean\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3 or rastersean\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle) and (distribut\$4 near2 (node)) or area-network\$3 or area-network\$3 or computemetwork\$3 or (cleares or semi-conductor or pellicle) and (distribut\$4 near2 (node)) or area-network\$3 or area-network\$3 or computemetwork\$3 or startsrean\$40 with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (duplex\$3 or sens\$4 or startsrean\$40 with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or wafer or semi-conductor or pellicle)) and (duplex\$3 or astersean\$40 with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or wafer or semi-conductor or pellicle)) and (duplex\$3 or astersean\$40 with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (duplex\$3 or astersean\$40 with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (duplex\$3 or astersean\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (duplex\$3 or astersean\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (duplex\$3 or astersean\$4) upper to per					
0 computertwork\$3 or (((Consister or communicat\$4)) near2 ((path or link\$3))), clm.)) not ((Cop0)Sectls or (438/5-18 ects. or (700/1-4.19.20.51,59.90.95.96,108-110,117,121 ects.))) and (((detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and ((distribut\$4 near2 (node)) or network\$3 or rous\$3 or ethermet or internet or LAN or WAN or SAN or area-network\$3 or metrology or measur\$5 or scan\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (duplex\$3 or believe) or wafer or semi-conductor or pellicle)) and (duplex\$3 or sensensan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (duplex\$3 or sensensan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (duplex\$3 or sensensan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (duplex\$3 or sensensan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (duplex\$3 or materscan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (buplex\$3 or materscan\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (buplex\$3 or materscan\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (buplex\$3 or materscan\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (buplex\$3 or materscan\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (buplex\$4 or materscan\$4) with (semiconductor or semi-conductor or pellicle)) and (buplex\$4 or matersc				IDM_TDB	
Inix\$33)), clm.)) not (709/8-cls. or (438/5-18.ccls. or 70071-4,192.0.51.59.99.59.6), 108-101.17, 121.ccls.))) and ((detect\$3 or sens\$3 or metrology or measur\$5 or sean\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3 or rastersean\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and ((distribut\$4) near2 (node)) or area-network\$3 or areametwork\$3 or computernetwork\$3 or (cleared or area or shot or defect\$4) with (semiconductor or communicat\$4) near2 (path or inix\$3)), clm.)) 34					
700/1-4,19.20,51,59,90,95,96,108-110,117,121.cels.))) and (((detected3 or senes3 or metrology or measur45 or sessands or SEM or (electron near2 microscop52) or inspect34 or raster\$3 or rasterszan34) with (die or die-to-die or area or shot or defect54) with (semiconductor or warer or semi-conductor or pellicle)) and ((distribut34 near2 (node)) or network33 or rout35 or ethernet or internet or LAN or WAN or SAN or area-network33 or computenterwork33 or ((transfer or communicat34) near2 (path or link33)),clm.)					
or sens33 or metrology or measur\$5 or sean\$4 or SEM or (clectron near2 microscop\$2) or inspect\$4 or near2 (node)) or network\$3 or rounnicat\$4) near2 (plant or link\$3)),etm.)) 34					
or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pelicle)) and (distribut\$4 hears; (node)) or network\$3 or rout\$3 or ethemet or internet or LAN or WAN or SAN or area-network\$3 or metrology or measur\$5 or sean\$4 or SEM or (electron near) microsop\$2) or inspect\$4 or raster\$3 or rastersean\$4\) with (die or die-to-die or area or shot or defect\$4\) with (semiconductor or pelicle) and (duplex\$3 or bi-directional\$2) or bi-directional\$2 or bidirectional\$2 or inspect\$4 or raster\$3 or rastersean\$4\) with (die or die-to-die or area or shot or defect\$4\) with (semiconductor or pelicle) and (duplex\$3 or bi-directional\$2 or bidirectional\$2). dlm 36					
network33 or rout33 or ethemet or internet or I.AN or WAN or SAN or are areanetwork33 or computementwork33 or ((transfer or communicat\$4) near2 (path or link33))).elm.)					
communicat54) near2 (path or link33)),clm.) ((detect33 or sens33 or metrology or measur55 or scan54 or SEM or (electron near2 microscop52) or inspect\$4 or raster53 or rasterscan54) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or bi-directional52 or bidirectional52) or bidirectional52 or bidirectional53 or scan54 or sEM or (clectron near2 microscop52) or inspect\$4 or raster\$3 or rasterscan54) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (duplex\$3 or bid-directional53 or bid-rectional52) clm. SPAT, US-PGPUB, EPO, JPO, DERWENT, BM_TDB (detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or (electron near2 microscop52) or inspect\$4 or raster\$3 or rasterscan54) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or pellicle)) and (duplex\$3 or bid-directional52 or bid-directional52) clm. SPAT, US-PGPUB, EPO, JPO, DERWENT, BM_TDB (detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (duplex\$3 or bid-directional\$2 or bid-rectional\$2) and (700% c.cls. or (709% c.cls. or (709% c.cls. or (709% c.cls. or (700% c					
13					
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48	183	or wafer or semi-conductor or pellicle)) and ((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.)) (column or composite-column) and (((detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or	DERWENT, IBM_TDB USPAT; US-PGPUB; EPO, JPO, DERWENT;	2004/07/10 19:03
49	29	pellicle)) and ((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.))) (column or composite-column).clm. and (((detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/10 19:03
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-	82	(SEM or (scan\$4 near2 electron)) and (709/\$.ccls.)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/07/10 15:31
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-	23	(700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls. and ((detect\$3 or sens\$3) with (die or die-to-die or area) with (semiconductor or wafer or semi-conductor))) and network	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO, JPO; DERWENT; IBM_TDB	2004/07/09 21:58